#### Partners









#### holofreeetch.eu



## **Project details**

Project number: 101161153

**Project name:** Novel approaches for halogen-free and sustainable etching of Silicon and Glass Project acronym: HaloFreeEtch Topic: HORIZON-EIC-2023-PATHFINDERCHALLENGES-01-04 Type of action: HORIZON-EIC Project starting date: 1 September 2024 **Project duration:** 48 EU Contribution: 3.997.735.00 Euro

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# **CHaloFreeEtch**

#### **Novel approaches for halogen**free and sustainable etching of Silicon and Glass

Funded by

### Project

HaloFreeEtch aims to revolutionize semiconductor manufacturing by developing an environmentally sustainable etching process that eliminates the use of halogenated compounds.

Funded by the European Union, this innovative initiative brings together leading experts from academia, research institutions, and industry to address the critical need for greener manufacturing technologies. By leveraging cutting-edge plasma etching techniques and advanced materials science, HaloFreeEtch strives to reduce the environmental footprint of semiconductor production while maintaining high performance and cost-effectiveness.

#### **Case Studies**



#### Development of a deep etching process for aapacitive sensors without halogens

Reduce environmental impact and improve process efficiency.



#### Multi-Scale modeling for etching process optimization

Development of multi-scale models to predict and optimize energy efficiency and etching speed.

